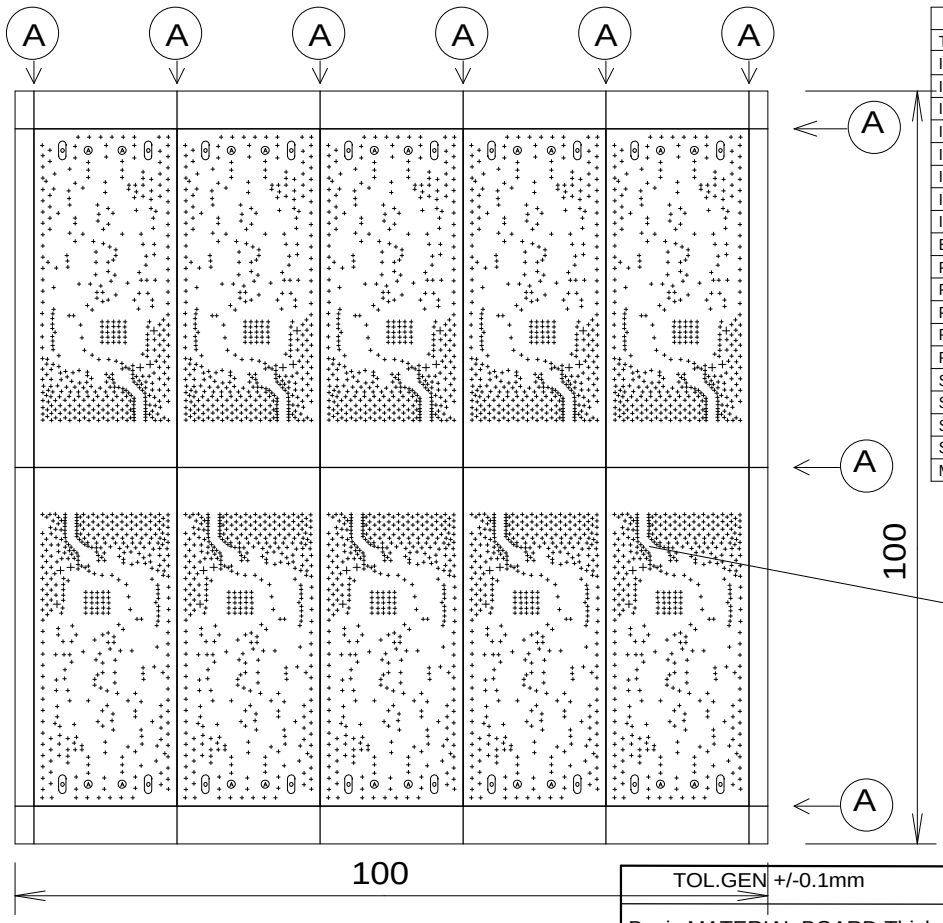
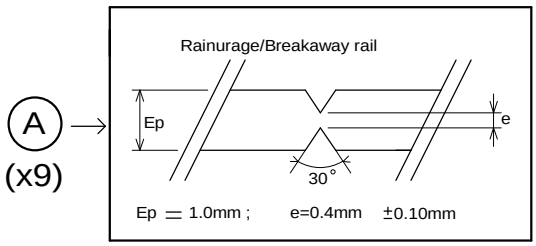


ARTWORKS	LAYER Nb	PCB	REV.	TYPE
TOP LAYER	1	PCB2428	2	311
INT. 2 LAYER	.	.	.	311
INT. 3 LAYER	.	.	.	311
INT. 4 LAYER	.	.	.	311
INT. 5 LAYER	.	.	.	311
INT. 6 LAYER	.	.	.	311
INT. 7 LAYER	.	.	.	311
INT. 8 LAYER	.	.	.	311
INT. 9 LAYER	.	.	.	311
BOTTOM LAYER	2	PCB2428	2	311
POWER_1	.	.	.	311
POWER_2	.	.	.	311
POWER_3	.	.	.	311
POWER_4	.	.	.	311
POWER_5	.	.	.	311
SOLDER MASK TOP	3	PCB2428	2	312
SOLDER MASK BOT	4	PCB2428	2	312
SILKSCREEN TOP	5	PCB2428	2	380
SILKSCREEN BOT	.	.	.	380
MILLING	6	PCB2428	2	313

Z = 50 Ohms (x10):
- TOP:Wire:660um,Space Wire/GND:150um.
- BOTTOM: Ref Layer.



LEGENDE DE PERCAGE / DRILL LEGEND				
ALL UNITS ARE IN MILLIMETERS				
FIGURE	DIAMETRE / HOLESIZE	PLATED	Qte / Qty	
·	0,20 mm +0,10 -0,05	PLATED	4120	<- VIA
+	0,30 mm (PERCE)	PLATED	30	
⊗	1,15 mm +0,10 -0,10	NON-PLATED	20	
⊖	1,0x2,5 mm +0,10 -0,05	PLATED	20	

TOL.GEN +/-0.1mm

STANDARD NFC 93-713

Basic MATERIAL,BOARD Thickness:FR4 Low CTEz TG150

Basic Copper thickness: CI:10/10mm;Cu:17,5um

MANUFACTURING Level [5]

SINGLE LAYER [.]

DOUBLE LAYER [X]

MULTILAYER [.] LAYERS (.)

SILKSCREEN [X] TOP [.] BOT COLOR [WHITE]

SOLDERMASK:

IMAGEABLE [X] TOP [X] BOT COLOR [RED]

OTHER [.] TOP [.] BOT

COATING COPPER

SnPb SELECTIVE [.]

SnPb CONSOLIDATED [.]

NI-AU [.] ELECTROLYTIC

[X] CHEMICAL

OTHER [.] : .

Date	Draw by	Verify	Modifications	IND.

Date : 23/11/15
Draw by : SR-ASCO
Checked by: M.BAUDRY
Project : JN5179

Material : .
File.

Finition : .

Protection : .

Marging : +/-0.1

Manufact.level : .

Scale : 1/1

Nbr of layers : .

Silkscreen
TOP :.
BOTTOM:.

NXP Semiconductors
2,Esplanade Anton Philips
Campus Effiscience Colombelles
BP 2000 - 14906 CAEN CEDEX 9

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DRILL MANUFACTURING
JN5179 USB DONGLE : OM15021-2

SIZE A4 | PCB2428-2-300 | REV. 00 | PL. 1/1